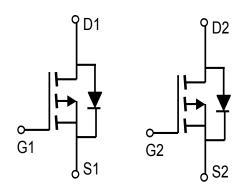


General Description

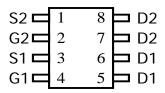
The AO4805 uses advanced trench technology to provide excellent $R_{DS(ON)}$, and ultra-low low gate charge with a 25V gate rating. This device is suitable for use as a load switch or in PWM applications.



Features

$$V_{DS}(V) = -30V$$

 $I_{D} = -9A$
 $R_{DS(ON)} < 15m\Omega (V_{GS} = 10V)$
 $R_{DS(ON)} < 19m\Omega (V_{GS} = 4.5V)$



Absolute Maximum Ratings T_A=25°C unless otherwise noted

Parameter Drain-Source Voltage Gate-Source Voltage		Symbol Maximum		Units	
		V _{DS}	-30	V	
			±20		
Continuous Drain	T _A =25°C		-8		
Current ^A	T _A =70°C	I_{D}	-6.9	Α	
Pulsed Drain Current ^B		I _{DM}	-40		
	T _A =25°C	D	2	W	
Power Dissipation ^A	T _A =70°C	-P _D	1.44	VV	
Junction and Storage Temperature Range		T_J , T_{STG}	-55 to 150	°C	

Thermal Characteristics

Parameter	Symbol	Тур	Max	Units	
Maximum Junction-to-Ambient ^A	t ≤ 10s	$ R_{\theta JA}$	50	62.5	°C/W
Maximum Junction-to-Ambient A	Steady-State	I \ _θ JA	73	110	°C/W
Maximum Junction-to-Lead ^C	Steady-State	$R_{ hetaJL}$	31	40	°C/W



Dual P-Channel MOSFET

Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions		Min	Тур	Max	Units
BV_{DSS}	Drain-Source Breakdown Voltage	I_D =-250 μ A, V_{GS} =0V		-30			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-24V, V _{GS} =0V T _J =55°C				-1	
						-5	μА
I_{GSS}	Gate-Body leakage current	V_{DS} =0V, V_{GS} =±20V				±100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS} I_{D}=-250\mu A$		-1	-1.5	-2.5	V
$I_{D(ON)}$	On state drain current	V _{GS} =-10V, V _{DS} =-5V		40			Α
		V _{GS} =-10V, I _D =-8A			12	15	mΩ
$R_{DS(ON)}$	Static Drain-Source On-Resistance	V_{GS} =-4.5V, I_{D} =-5A			16	19	mΩ
g _{FS}	Forward Transconductance	V_{DS} =-5V, I_{D} =-8A		16	21		S
V_{SD}	Diode Forward Voltage	I _S =-1A,V _{GS} =0V			-0.75	-1	V
I _S	Maximum Body-Diode Continuous Current					-2.6	Α
C _{iss}	Input Capacitance				2076		pF
C _{oss}	Output Capacitance	V _{GS} =0V, V _{DS} =-15V, f=1MHz			503		pF
C _{rss}	Reverse Transfer Capacitance				302		рF
R_g	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1MHz			2		Ω
Q_g	Total Gate Charge				39		nC
Q_{gs}	Gate Source Charge	V _{GS} =-10V, V _{DS} =-15V, I _D =-8A			8		nC
Q_{gd}	Gate Drain Charge				11.4		nC
t _{D(on)}	Turn-On DelayTime				12.7		ns
t _r	Turn-On Rise Time	V_{GS} =-10V, V_{DS} =-15V, R_{L} =1.8 Ω , R_{GEN} =3 Ω			7		ns
$t_{D(off)}$	Turn-Off DelayTime				25.2		ns
t _f	Turn-Off Fall Time				12		ns
t _{rr}	Body Diode Reverse Recovery Time	I _F =-8A, dI/dt=100A/μs			32		ns
Q _{rr}	Body Diode Reverse Recovery Charge	I _F =-8A, dI/dt=100A/μs		_	26		nC

A: The value of $R_{\theta,JA}$ is measured with the device mounted on 1in^2 FR-4 board with 2oz. Copper, in a still air environment with T_A =25°C. The value in any a given application depends on the user's specific board design. The current rating is based on the t≤ 10s thermal resistance rating.

B: Repetitive rating, pulse width limited by junction temperature.

C. The R $_{\theta JA}$ is the sum of the thermal impedence from junction to lead R $_{\theta JL}$ and lead to ambient.

D. The static characteristics in Figures 1 to 6,12,14 are obtained using $80\mu s$ pulses, duty cycle 0.5% max.

E. These tests are performed with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T_A =25 °C. The SOA curve provides a single pulse rating.



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

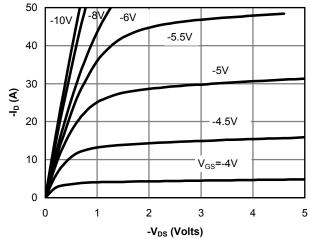


Fig 1: On-Region Characteristics

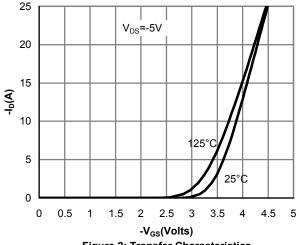


Figure 2: Transfer Characteristics

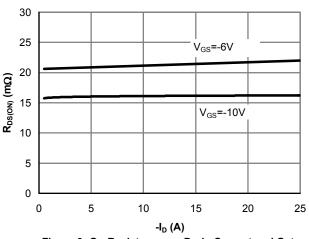


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

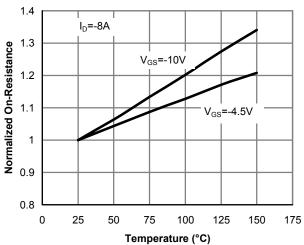


Figure 4: On-Resistance vs. Junction Temperature

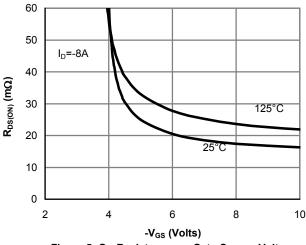


Figure 5: On-Resistance vs. Gate-Source Voltage

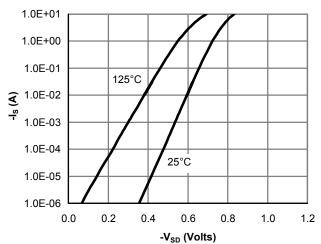


Figure 6: Body-Diode Characteristics



Dual P-Channel MOSFE

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

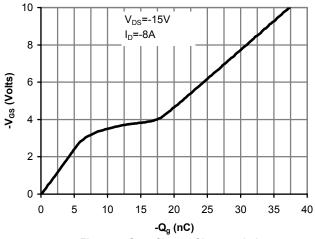


Figure 7: Gate-Charge Characteristics

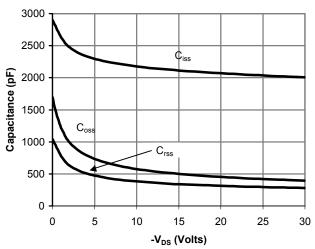


Figure 8: Capacitance Characteristics

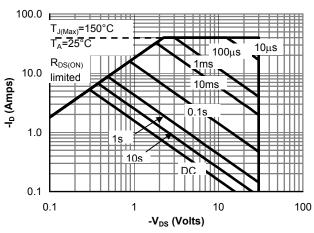


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

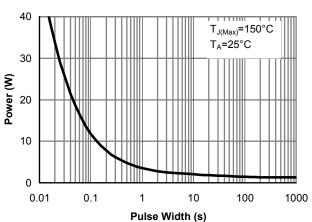


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

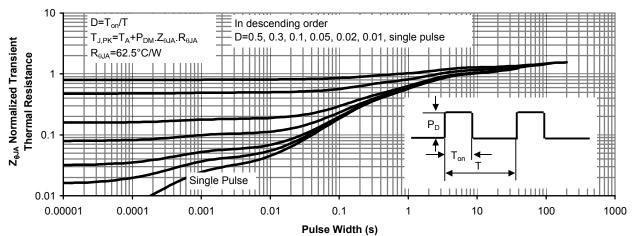
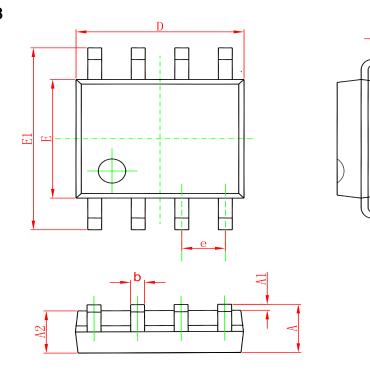


Figure 11: Normalized Maximum Transient Thermal Impedance



PACKAGE OUTLINE DIMENSIONS

SOP-8

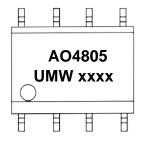


Cumbal	Dimensions In Millimeters		Dimensions In Inches			
Symbol	Min	Max	Min	Max		
Α	1.350	1.750	0.053	0.069		
A1	0.100	0.250	0.004	0.010		
A2	1.350	1.550	0.053	0.061		
b	0.330	0.510	0.013	0.020		
С	0.170	0.250	0.006	0.010		
D	4.700	5.100	0.185	0.200		
Е	3.800	4.000	0.150	0.157		
E1	5.800	6.200	0.228	0.244		
е	1.270	1.270(BSC)		0.050(BSC)		
L	0.400	1.270	0.016	0.050		
θ	0°	8°	0°	8°		





Marking



("xxxx"代表年份周期)

Ordering information

Order code	Package	Baseqty	Deliverymode
UMW AO4805	SOP-8	3000	Tape and reel